Press release for immediate publication

ASIC service – a global offering for integrated circuit development

Neuchâtel, 30 June 2008 – CSEM's Application Specific Integrated Circuit (ASIC) customers now have a single point of entry for a complete range of services. In January 2007, CSEM responded to customer feedback that requested a complete ASIC service by developing a solution aligned with the organization's mission to facilitate technology transfer. This new approach to developing and industrializing CMOS integrated circuits and image sensors makes CSEM an ideal partner for customers requiring a full ASIC service.

A 'one-stop shop' from design to production

By designing innovative low-power and/or low-voltage system-on-chips (SoCs), CSEM is now able to propose a global offering to its customers. The mission of our ASIC service is to bridge the industrialization gap for small- to medium-volume production, and to foster the transfer of CSEM's integrated circuit (IC) technology to industrial products.

The services on offer comprise essentially the design, industrialization and production of complex analog/digital/RF and high-performance image-sensing SoCs. CSEM manages ASIC prototyping, industrialization, testing, and production using a network of selected third parties, and has set up a test lab for optoelectronic characterization of image sensors and complete visions systems. The lab combines optical and microelectronic testing procedures to fully qualify image sensors and vision systems.Since the creation of its ASIC service, CSEM has joined the Global Semiconductor Alliance (GSA), promoting collaboration, integration, and innovation within the global semiconductor industry.

Valuable customer benefits from a new service model

Working with CSEM brings significant benefits to ASIC customers, who now have one partner company from circuit and imager specification to production. High flexibility, in terms of prototyping and managing relatively small production volumes, is complemented by CSEM's industrial experience in designing innovative, lowest-power CMOS ICs and image sensors.

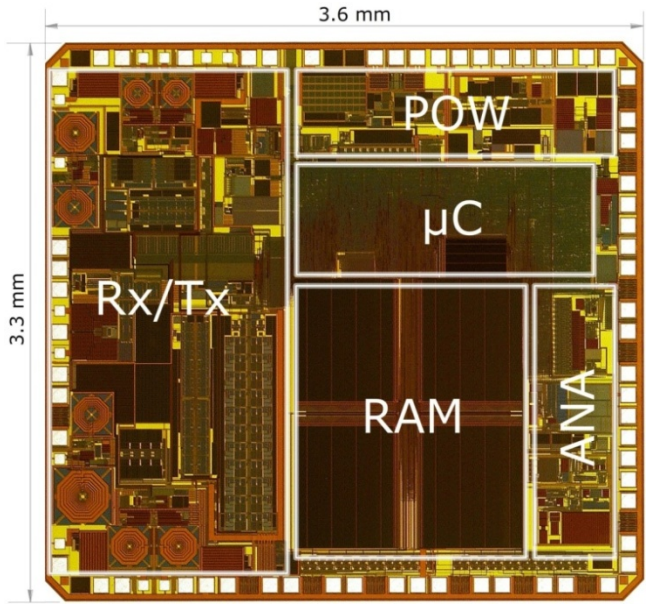


Image 1: WiseNet SoC in TSMC 0.18 µm technology.
This low-power chip combines a sub-gigahertz radio transceiver, an 8-bit microcontroller, memories (SRAM and ROM), complex power management, an AD converter, and a sensor interface, all on 11.88 mm^2 of silicon surface.

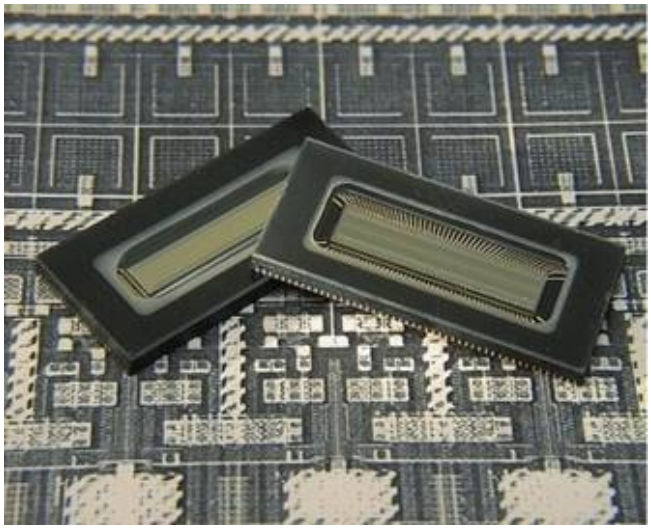


Image 2: Line sensors.
High-speed CMOS image sensors detect up to 80,000 images a second.

Additional information

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CSEM – an innovation center

Established in 1984, CSEM (Centre Suisse d'Electronique et de Microtechnique SA) is a private R&D center specializing in microtechnology, nanotechnology, microelectronics, systems engineering and communications technologies. It provides its industry customers and partners with tailor-made, innovative product solutions based on its commercial and technological expertise, further expanded by the results of its applied research. Additionally, through the establishment of start-up businesses, it actively contributes to developing Switzerland as a center of industry and commerce. To date, CSEM has established a total of 25 new enterprises with more than 500 employees.

About 350 highly qualified employees from the most varied scientific and technical fields work for CSEM in Neuchâtel, Basel, Zurich, Alpnach, and Landquart. They represent more than 20 different nationalities and constitute the basis of the company's creativity, dynamism and innovation potential.

Further information is available at www.csem.ch

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